

DEVICE	Package Type	Material	Supplier	Type	Compisition	CAS No.	% of weight	Appendix	Weight(mg)	ICP报告	MSDS	
LS98002	QFN-14L-1.6X2.0X0.55-A_P0.4	Wafer	-	-	-	-	100%	N/A	0.35			
		Lead Frame	新恒汇	C194	Iron	7439-89-6	2.097-2.276%	N/A	73.82			
					Phosphorus	7723-14-0	0.015-0.131%					
					Zinc	7440-66-6	0.050-0.175%					
					Copper	7440-50-8	84.929-97.718%					
					Silver	7440-22-4	0.120-12.480%					
					Lead	7439-92-1	0.000-0.009%					
		Flux	INDIUM	TACFLUX 026S	POLYGLYCOL ETHER	9038-95-3	80-85%	N/A	0.97			
					CARBOXYLIC ACID	68937-68-8	5-10%					
					AMIDES	68876-81-3	5-10%					
		Molding Compound	Hitachi	CEL-9220HF13X-D-M3	环氧树脂1	商业机密	2~5	N/A	65.047			
					环氧树脂2	商业机密	0.5~4					
					硬化剂	商业机密	2~5					
					金属氢氧化物	商业机密	1~10					
					碳黑	1333-86-4	接近0.2					
					二氧化硅1	60676-86-0	65~90					
					二氧化硅2	7631-86-9	0~15					
		Plating	YT	Matte Tin	Tin	7440-31-5	99.90%	N/A	1.52			
		Total=								141.707		